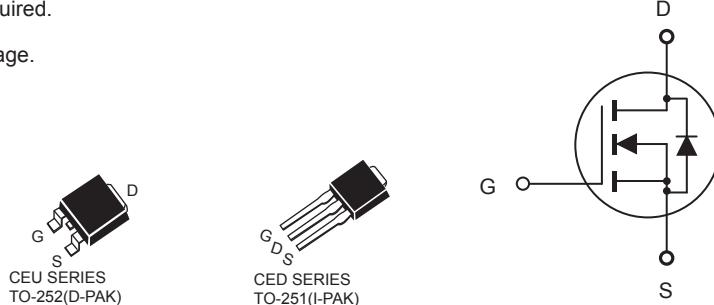


**N-Channel Enhancement Mode Field Effect Transistor****FEATURES**

- 60V, 50A,  $R_{DS(ON)} = 8.7m\Omega$  @ $V_{GS} = 10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.

**ABSOLUTE MAXIMUM RATINGS**  $T_C = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	50	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	200	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	$P_D$	50 0.33	W W/ $^\circ C$
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 175	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	3	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	50	$^\circ C/W$



# CED6086/CEU6086

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 24\text{A}$		6.7	8.7	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2420		pF
Output Capacitance	$C_{\text{oss}}$			235		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			150		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 4.7\Omega$		13	26	ns
Turn-On Rise Time	$t_r$			4	8	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			45	90	ns
Turn-Off Fall Time	$t_f$			6	12	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 48\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		50	65	nC
Gate-Source Charge	$Q_{\text{gs}}$			8		nC
Gate-Drain Charge	$Q_{\text{gd}}$			16		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				40	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 40\text{A}$			1.2	V
<b>Notes :</b>						
a.Repetitive Rating : Pulse width limited by maximum junction temperature.						
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$ .						
c.Guaranteed by design, not subject to production testing.						
d.L = 0.1mH, $I_{AS} = 42\text{A}$ , $V_{DD} = 24\text{V}$ , $R_G = 25\Omega$ , Starting $T_J = 25^\circ\text{C}$						

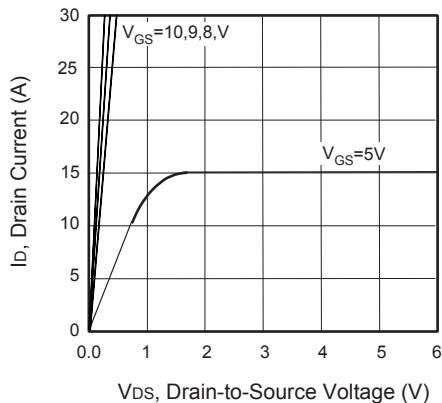


Figure 1. Output Characteristics

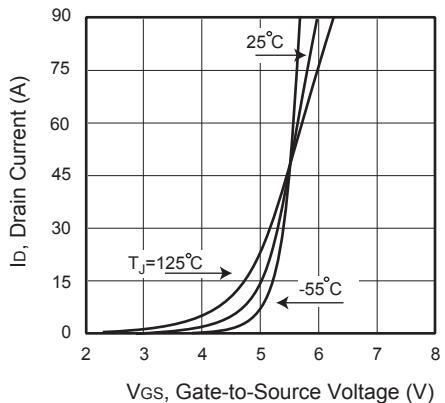


Figure 2. Transfer Characteristics

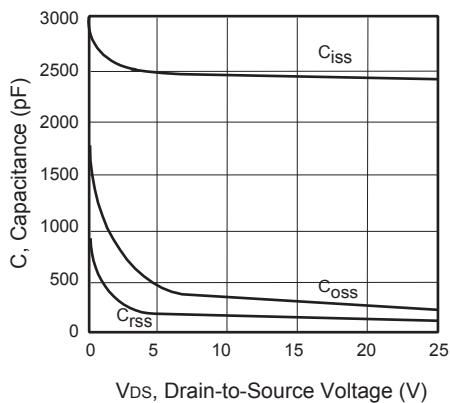


Figure 3. Capacitance

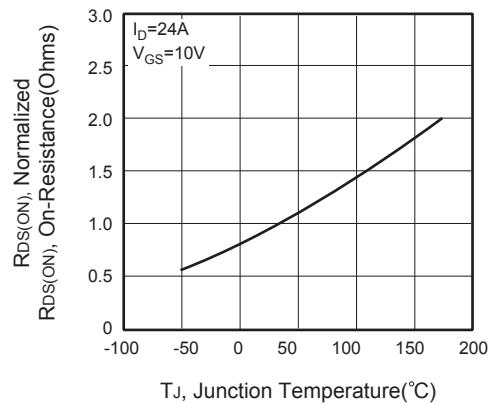


Figure 4. On-Resistance Variation with Temperature

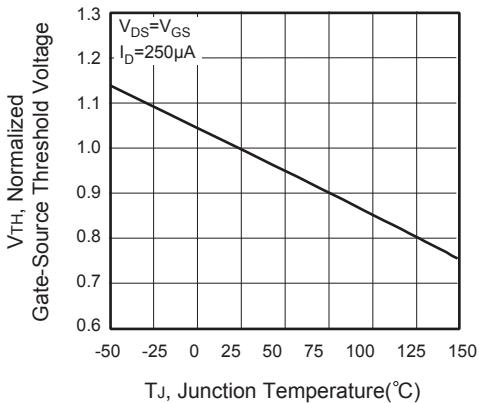


Figure 5. Gate Threshold Variation with Temperature

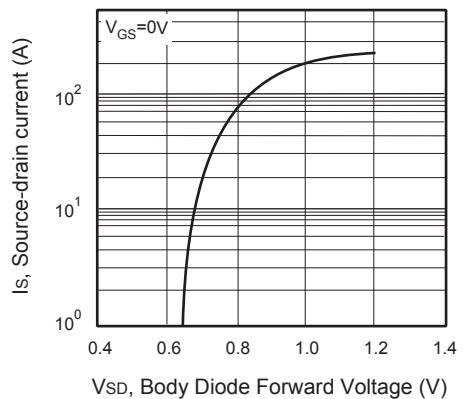
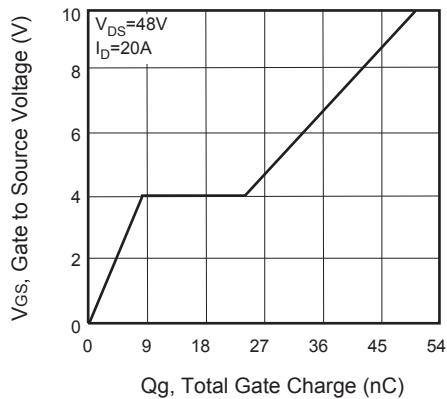
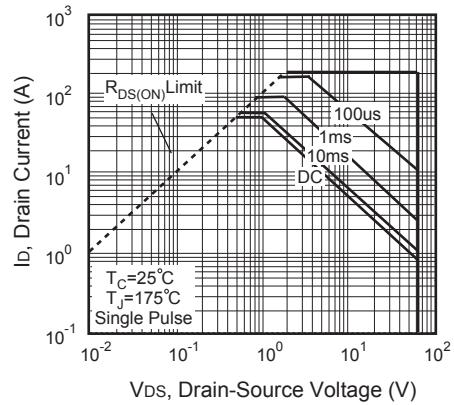


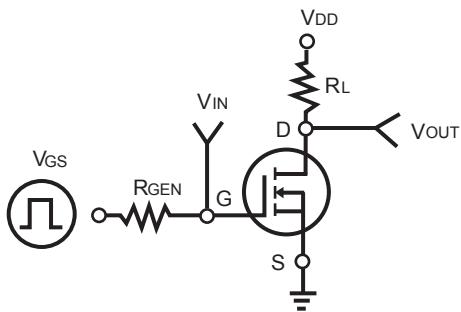
Figure 6. Body Diode Forward Voltage Variation with Source Current



**Figure 7. Gate Charge**



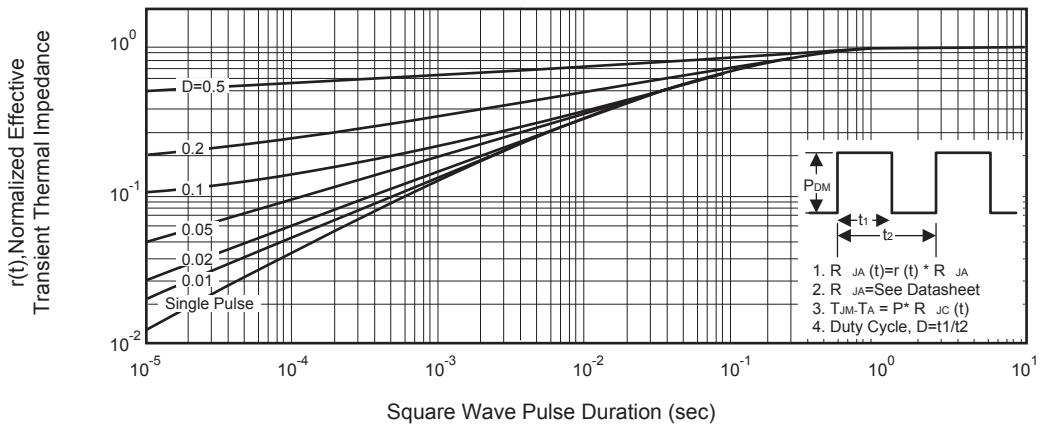
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**